

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
17 February 2022 (17.02.2022)



(10) International Publication Number
WO 2022/035542 A1

(51) International Patent Classification:

H01L 21/67 (2006.01) B23K 26/38 (2006.01)
H01L 21/677 (2006.01)

(21) International Application Number:

PCT/US2021/041473

(22) International Filing Date:

13 July 2021 (13.07.2021)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

16/989,746 10 August 2020 (10.08.2020) US

(71) Applicant: **APPLIED MATERIALS, INC.** [US/US];
3050 Bowers Avenue, Santa Clara, CA 95054 (US).

(72) Inventors: **THIRUNAVUKARASU, Sriskantharajah**;
82 Springside View, Singapore, 786129 (SG). **BAL-
AKRISHNAN, Karthik**; 987 Bukit Timah Road, #03-16,
Maple Woods, Singapore, 589628 (SG). **ELUMALAI,**

Karthik; #57, Toh Tuck Road, Singapore, 596295 (SG).
PEH, Eng Sheng; Block 327C, Anchorvale Road, Unit
10-308, Singapore, 543327 (SG).

(74) Agent: **BERNADICOU, Michael, A.** et al.; Schwabe,
Williamson & Wyatt, P.C., 1211 Sw 5th Avenue, Suite
1900, Portland, OR 97204 (US).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO,
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN,
HR, HU, ID, IL, IN, IR, IS, IT, JO, JP, KE, KG, KH, KN,
KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD,
ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO,
NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW,
SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN,
TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,

(54) Title: MAINFRAME-LESS WAFER TRANSFER PLATFORM FOR WAFER PROCESSING MODULES

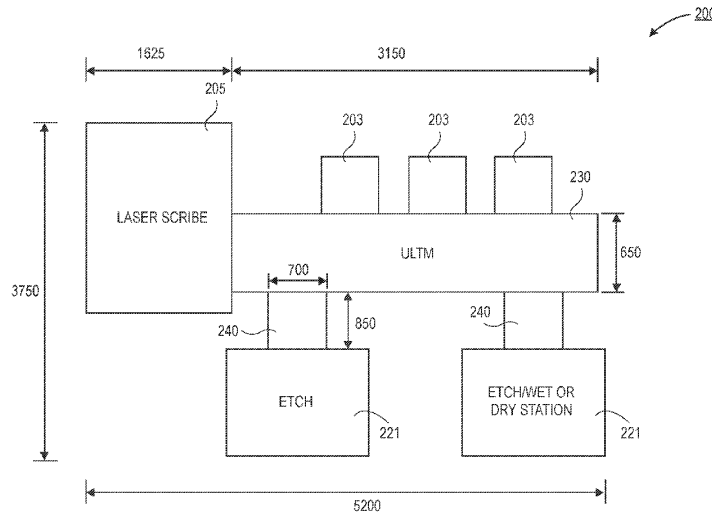


FIG. 2A

(57) Abstract: In an embodiment, a semiconductor processing tool for implementing hybrid laser and plasma dicing of a substrate is provided. The semiconductor processing tool comprises a transfer module, where the transfer module comprises a track robot for handling the substrate, and a loadlock attached to the transfer module. In an embodiment, the loadlock comprises a linear transfer system for handling the substrate. In an embodiment, the processing tool further comprises a processing chamber attached to the loadlock, wherein the linear transfer system of the loadlock is configured to insert and remove the substrate from the processing chamber.

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GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))